SLIP 2014 Technical Program
June 1st, 2014
Co-located with DAC in San Francisco
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Breakfast (8:00am-8:30am)

Opening Remarks (8:30am-8:40am)

Session I: 3D Integration (Chair: Akhilesh Kumar, Intel)
  • 8:40am – 9:10am: “Compact Models and Model Standard for 2.5D and 3D Integration”, Qiaosha Zou and Yuan Xie, Penn State Univ. (INVITED)
  • 9:10am – 9:40am: “Computing in 3D”, Paul Franzon, NC State Univ. (INVITED)
  • 10:10am – 10:25am: Post-session Review Panel (Expert Panelist: Akhilesh Kumar, Intel)

Break (10:25am – 10:45am)

Session II: Power and Clock Delivery (Cliff Sze, IBM)
  • 10:45am – 11:05am: “Power Network On-Chip for Scalable Power Delivery”, Inna Vaisband and Eby Friedman, Univ. of Rochester
  • 11:45am – 12:00pm: Post-session Review Panel (Expert Panelist: Cliff Sze, IBM)

Lunch (12:00pm – 1:00pm)

Session III: Routing (Chair: Chung-Kuan Cheng, UC San Diego)
  • 1:00pm – 1:30pm: “Manufacturable and Reliable Interconnect in Extreme Scaling”, David Pan, UT Austin (INVITED)
  • 1:30pm – 1:50pm: “UI-Route: An Ultra-Fast Incremental Maze Routing Algorithm”, Tsung-Wei Huang, Pei-Ci Wu and Martin D. F. Wong, UIUC
  • 2:10pm – 2:30pm: “Methodology for Electromigration Signoff in the Presence of Adaptive Voltage Scaling”, Wei-Ting Chan, Andrew B. Kahng and Siddhartha Nath, UC San Diego
  • 2:30pm – 2:45pm: Post-session Review Panel (Expert Panelist: Chung-Kuan Cheng, UC San Diego)

Break (2:45pm – 3:00pm)
FINAL PROGRAM

Poster Session and Networking
3:00pm – 3:30pm
• “Site Functions for 3D ICs Considering Impacts of TSVs”, Masoud Zabihi, Farzad Radfar and Reza Sarvari, Sharif Univ. of Technology
• “Toward Assessment of True 3D Design Benefits over 2D Implementation”, Tuck-Boon Chan, Andrew B. Kahng, Ilgweon Kang, Hyein Lee and Jiajia Li, UC San Diego

Invited Talk: On AMBA Interconnect (Rob Aitken, ARM)
3:30pm – 4:00pm

Panel: Emerging Technologies and Networks-on-Chip (NoC) Design (Chair: Umit Ogras, ASU)
4:00pm – 5:00pm
Panelists:
• Prof. Yuan Xie, The Pennsylvania State Univ., “NoCs with 3D IC technology”
• Prof. Partha Pratim Pande, Washington State Univ., “NoCs with wireless communication technology”
• Prof. Wim Boaerts, Ghent Univ. – IMEC, “NoCs with Optical Communication Technology”
• Dr. Akhilesh Kumar, Intel Corporation, “High bandwidth industrial NoC design”

Dinner (6:30pm)
General Chair
Rasit O. Topaloglu
IBM, USA

Technical Program Chair
Sung Kyu Lim
Georgia Institute of Technology, USA

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Baris Taskin
Drexel University, USA

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